PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

 SUBMISSION TYPE:
 NEW ASSIGNMENT

 NATURE OF CONVEYANCE:
 ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SU KON KIM	07/17/2005

RECEIVING PARTY DATA

Name:	DongbuAnam Semiconductor Inc.	
Street Address:	891-10, Daechi-Dong, Kangnam-Ku	
City:	Seoul	
State/Country:	KOREA, REPUBLIC OF	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11184289

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: OPP-GZ-2005-0017-US-00

NAME OF SUBMITTER: Alec B. Plumb, Reg. No. 56,433

Total Attachments: 1

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JP \$40.00 111842

PATENT REEL: 017056 FRAME: 0596 of the Republic of Korea

a corporation

Attorney Docket No.: OPP-GZ-2005-0017-US-00

Do hereby sell, assign and transfer to DongbuAnam Semiconductor Inc.

ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, the undersigned,

SU KON, KIM

who have created a certain invention for which an application for United States Letters Patent was executed by me on October 19, 2004 and entitled:

METHOD FOR FABRICATING CMOS IMAGE SENSOR

at 891-10, Daechi-dong, Kangnam-ku, Seoul, Körea is successors, assigns, and Jegal representatives, the full and exclusive right to said invention and said application and to any and all inventions described in said application for the United States, its trottorial possessions and all foreign countries, and the united States, its territorial possessions and all foreign countries; and in and to any and all centinuations-in-part, continuations, divisions, substitures, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its and all rights, together with all priority rights, under any of the international conventions, unions, agreements, and all readies, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, unions, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties, including all future conventions, assigns, on the representatives, and all divertions, the referred to as Assignee, its successors, assigns, or legal representatives all facts known to the undersigned relating to said invention and the history thereof, and generally do everything possible which said Assignee, its successors, assigns, or legal representatives that no assignment, prant, mortgage, liceuse or other ag	of the Republic of Korea	having a place of business
application and to any and all inventions described in said application for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties; Agree that DonghuAnam Semiconductor Inc. hereinafter referred to as Assignee, may apply for and receive Letters Patent for said invention and said inventions, hereinafter referred to as said invention, in its own name, in the United States, its territorial possessions, and all foreign countries; and that, when requested to carry out in good faith, the intent and purpose of this assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or legal representatives that no assignment, grant protection for said invention and for vesting title to said invention and all applications for patents on said invention in said Assignee, its successors, assigns, or legal representatives that no assignment, grant mortgage, license or other agreemen	at 891-10, Dacchi-dong, Kangnam-ku, Scoul, Korea	•
apply for and receive Letters Patent for said invention and said inventions, hereinafter referred to as said invention, in its own name, in the United States, its territorial possessions, and all foreign countries; and that, when requested to carry out in good faith the intent and purpose of this assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof, and generally do everything possible which said Assignee, its successors, assigns, or legal representatives shall consider desirable for adding in securing, maintaining and enforcing proper patent protection for said invention and for vesting title to said invention and all applications for patents on said invention in said Assignee, its successors, assigns, or legal representatives; and Covenant with said Assignee, its successors, assigns, or legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned. IN TESTIMONY WHEREOF I have hereunto set MY signature on the date indicated below. Full Name of Sole/First Inventor: Date: Month/Day/Year Full Name of Sole/First Inventor; if any:	application and to any and all inventions described in sepossessions and all foreign countries, and the entire right, the which may be granted therefor in the United States, its tenend to any and all continuations-in-part, continuations, divise other applications for Letters Patent relating thereto which territorial possessions and/or any foreign countries, and all the international conventions, unions, agreements, acts, and	aid application for the United States, its territorial title and interest in and to any and all Letters Patent ritorial possessions and all foreign countries; and in the sions, substitutes, reissues, extensions thereof, and all have been or shall be filed in the United States, its rights, together with all priority rights, under any of
mortgage, liceuse or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned. IN TESTIMONY WHEREOF I have hereunto set MY signature on the date indicated below. Full Name of Sole/First Inventor: SU KON, KIM Inventor's Signature: Date: Month/Day/Year Full Name of Second Inventor, if any:	apply for and receive Letters Patent for said invention a invention, in its own name, in the United States, its territor when requested to carry out in good faith the intent and Assignce, its successors, assigns and legal representatives, part, continuations, divisions, substitutes, reissues, extension powers of attorney and other papers, testify in any legal Assignce, its successors, assigns or legal representatives a invention and the history thereof; and generally do everytassigns, or legal representatives shall consider desirable for a patent protection for said invention and for vesting title to said	and said inventions, hereinafter referred to as said rial possessions, and all foreign countries; and that, purpose of this assignment, at the expense of said, the undersigned will execute all continuations-inous thereof, execute all rightful oaths, assignments, or quasi legal proceedings; communicate to said all facts known to the undersigned relating to said thing possible which said Assignee, its successors, adding in securing, maintaining and enforcing proper aid invention and all applications for paients on said
IN TESTIMONY WHEREOF I have hereunto set MY signature on the date indicated below. Full Name of Sole/First Inventor: SU KON, KIM Inventor's Signature: Date: Month/Day/Year Full Name of Second Inventor, if any:	mortgage, license or other agreement affecting the rights and	d property herein conveyed has been made to others
SU KON, KUM Inventor's Signature: Date: Month/Day/Year Full Name of Second Inventor, if any:		
Inventor's Signature: Date: Month/Day/Year Full Name of Second Inventor, if any:	Full Name of Sole/First Inventor:	
Full Name of Second Inventor, if any:	SU KON, KUM	
	Inventor's Signature;	Date: Month/Day/Year
	Full Name of Second Inventor, if any:	
Inventor's Signature: Date: Month/Day/Year		
	Inventor's Signature	Daniel Daniel
	we should a diguate of	Date: Month Day Year

Customer No. 36872

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